

Marking Information

Site 1



M6 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2016	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	D	 Н	I	J	K	L	М	N	0	Р	R
Code	D	 H	I	J	K	L	M	N	0	P	ŀ

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2



M6 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2016	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	6	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	Х	Υ	Z



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		VDSS	30	V	
Gate-Source Voltage		V_{GSS}	±12	V	
Continuous Drain Current (Note 6) VGS = 4.5V	lo	5.0 4.0	А		
Maximum Continuous Body Diode Forward Curren	nt (Note 6)		Is	1.5	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1	%)	I _{DM}	25	А	
Avalanche Current (Note 7) L = 0.1mH		las	11	Α	
Avalanche Energy (Note 7) L = 0.1mH			Eas	6	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C	Pn	0.81	W	
Total Fower Dissipation (Note 5)	T _A = +70°C	PD	0.52	, vv	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	132	°C/W	
Thermal Nesistance, sunction to Ambient (Note 3)	t<10s	RθJA	101	C/VV	
Total Power Dissipation (Note 6)	$T_A = +25$ °C	Pp	1.36	W	
Total Fower Dissipation (Note o)	T _A = +70°C	Pυ	0.87	v v	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	83		
Thermal Nesistance, sunction to Ambient (Note o)	t<10s	Keja	60	°C/W	
Thermal Resistance, Junction to Case (Note 6)		Rejc	10		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

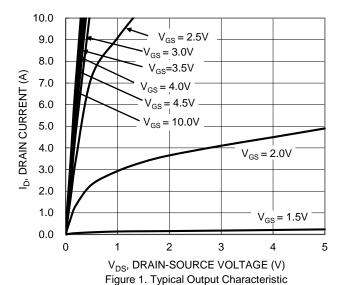
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

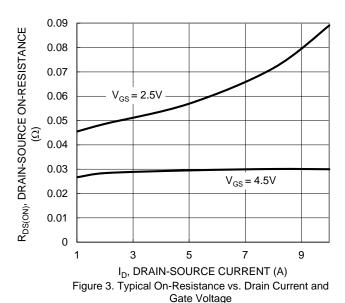
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)			-			
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current, TJ = +25°C	IDSS	_	_	1.0	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance		_	32	40	mΩ	$V_{GS} = 4.5V, I_{D} = 3A$
Static Drain-Source On-Resistance	Rds(on)	_	52	75	m77	V _G S = 2.5V, I _D = 2A
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 2A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	458		рF	\\ 45\\\\\ 0\\
Output Capacitance	Coss	_	50	_	pF	V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	44	_	pF	1 = 1.0WHZ
Gate Resistance	R_g	_	2.1	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 10V)	Qg	_	11.2	_	nC	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	5.3	_	nC	\/ 45\/ I- 4A
Gate-Source Charge	Qgs	_	1.1	_	nC	V _{DS} = 15V, I _D = 4A
Gate-Drain Charge	Q _{gd}	_	1.8	_	nC	
Turn-On Delay Time	tD(ON)	_	1.8	_	ns	
Turn-On Rise Time	t _R	_	2.6	_	ns	V _{DS} = 15V, V _{GS} = 10V,
Turn-Off Delay Time	t _{D(OFF)}	_	9.5	_	ns	$R_g = 6\Omega$, $R_L = 3.75\Omega$
Turn-Off Fall Time	tF	_	2.1	_	ns	1
Reverse Recovery Time	trr	_	7.0	_	ns	
Reverse Recovery Charge	Q _{RR}	_	1.8	_	nC	$I_F = 3A$, di/dt = 100A/ μ s

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Device mounted on FR-4 substrate PC board, 202 copper, with minimum recommended particles.
Les mounted on FR-4 substrate PC board, 202 copper, with 1inch square copper plate.
I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.







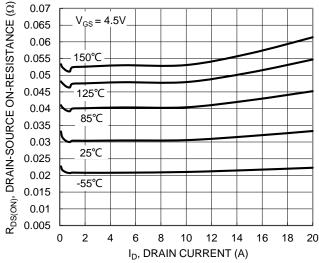
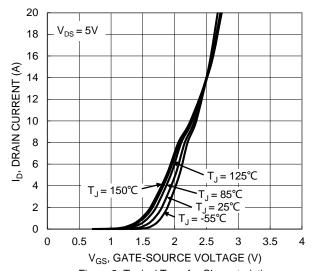
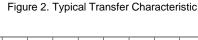


Figure 5 . Typical On-Resistance vs. Drain Current and Temperature





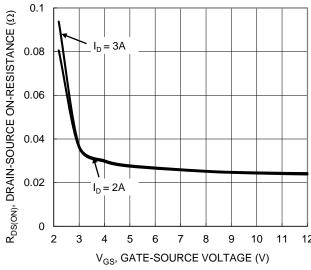


Figure 4 . Typical Transfer Characteristic

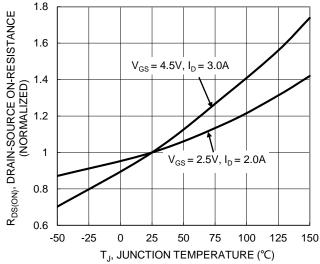


Figure 6. On-Resistance Variation with Temperature



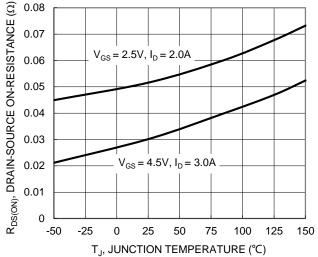
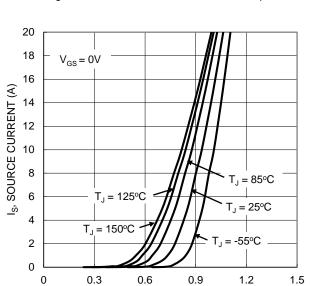


Figure 7. On-Resistance Variation with Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

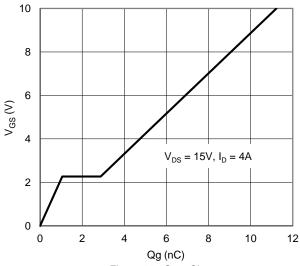


Figure 11. Gate Charge

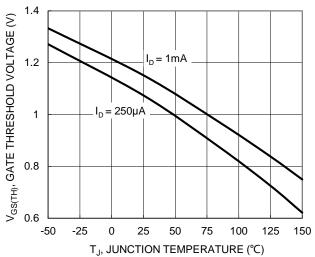
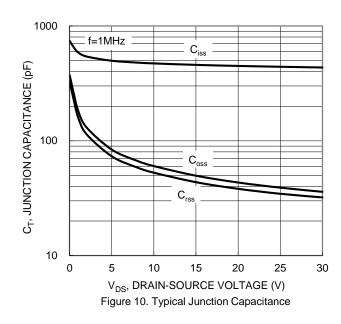
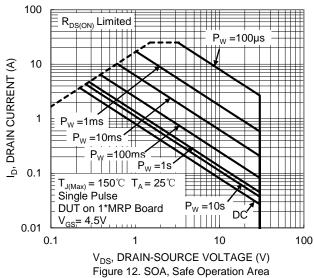


Figure 8. Gate Threshold Variation vs. Junction Temperature







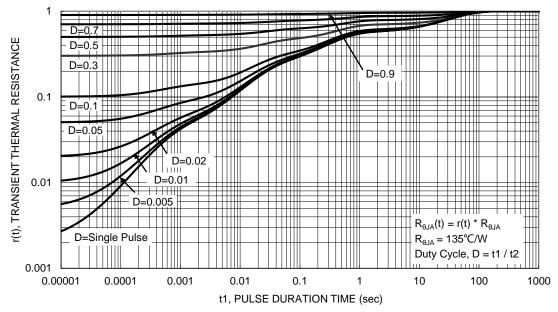


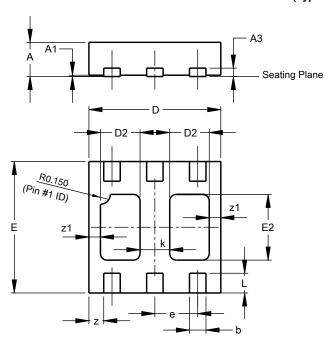
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)

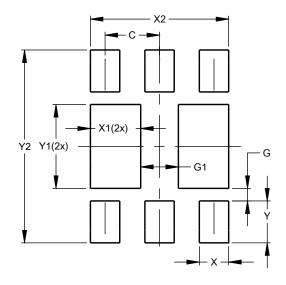


	U-DFN2020-6						
(Type B)							
Dim	Min	Max	Тур				
Α	0.545	0.605	0.575				
A1	0.00	0.05	0.02				
A3	-	-	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
D2	0.50	0.70	0.60				
е	-	-	0.65				
Е	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
k	-	-	0.45				
L	0.25	0.35	0.30				
Z	-	-	0.225				
z1	-	-	0.175				
All	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value (in mm)
С	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Υ	0.500
Y1	1.000
Y2	2.300



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